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THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 5067**
Mizuki NAGAI et al. : Docket No. 2003_1338
Serial No. 10/664,078 : Group Art Unit 1753
Filed September 17, 2003 : Examiner Edna Wong

COPPER-PLATING LIQUID, PLATING
METHOD AND PLATING APPARATUS

Mail Stop: Amendment

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reply to the Notice of Non-Compliant Amendment dated July 21, 2005, please amend the present application as follows: